At A Glance

IBM has built the first PowerPC chips and delivered samples to Apple. The chip uses a modified RSC core with a bus interface similar to the 88110, achieving impressive performance with a relatively small die.
RISC's Adjust Course Downward
Most Significant Bits
SPARC Hits Low End with TI's microSPARC
Hobbit Enables Personal Communicators
ARM250 Integrates RISC System on a Chip
Intel Describes P5 Internal Architecture
Recent IC Announcements
Resources
Literature Watch will return next issue.

MICROPROCESSOR ♥ REPORT

THE INSIDERS' GUIDE TO MICROPROCESSOR HARDWARE

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